# Monthly LabAdviser update: 12/3 2018

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| Updated Subject | Contributor | Link to the updated pages |
| **LPCVD nitride**  Stress measurements of LPCVD nitride films | **Martin Lind Ommen @Nanotech** | [LPCVD\_nitride\_furnace#Stress\_measurements](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Furnace_LPCVD_Nitride/Deposition_of_stoichiometric_nitride_using_the_4%22_LPCVD_nitride_furnace#Stress_measurements)  [Deposition\_of\_low\_stress\_nitride\_using\_the\_6%22\_LPCVD\_nitride\_furnace](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Furnace_LPCVD_Nitride/Deposition_of_low_stress_nitride_using_the_6%22_LPCVD_nitride_furnace) |
| **PECVD – conformity**  SEM images of the conformity of PECVD glass from PECVD4 | **Lasse H. Thamdrup @NILT** | [PECVD/conformity#SiO2\_deposition\_on\_holes\_with\_diameter\_431nm-442nm\_nad\_depth\_257\_nm](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide/Deposition_of_Silicon_Oxide_using_PECVD/conformity#SiO2_deposition_on_holes_with_diameter_431nm-442nm_nad_depth_257_nm) |
| **RCA**  Process description and background information updated | **Claus H. Nielsen @danchip** | [Wafer\_cleaning/RCA](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Wafer_cleaning/RCA) |
| **Polymer Injection Molder**  General update and new section describing the most important injection molding machine parameters. | **Claus H. Nielsen @danchip** | [Polymer\_Injection\_Molder](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Polymer_Injection_Molder) |
| **Hardness measurement (new page)**  New page describing capabilities of the Vickers hardness tester available in the cleanroom | **Claus H. Nielsen @danchip** | [Hardness\_measurement](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/Hardness_measurement) |

# Equipment Manuals updated in LabManager:

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

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| |  | | --- | | 5. 3. 6.01) Manual for Flip Chip bonder, ver 4  5. 3. 1.12) Manual for MVD, ver 4  5. 3. 6.12) Manual for Ball wire-bonder, ver 2.1  5. 3. 3.05) Manual for ASE, ver 2  5. 3. 7.07) Manual for Drop Shape Analyzer, ver 2  5. 3. 2.08) Manual for PECVD3, ver 1.6  5. 3. 1.10) Manual for KS Aligner\_ MA6, ver 6  5. 3. 1.17) Manual for DUV Stepper., ver 3  5. 3. 1.30) Manual for SÜSS Spinner-Stepper., ver 3  5. 3. 1.38) Manual for Hotplate: 90-110C, ver 2  5. 3. 6.04) Manual for Polisher/Lapper, ver 1.2  5. 3. 6.14) Manual for Vacuum Sealer, ver  5. 3. 7.51) Manual for Hardness tester, ver 1  5. 3. 6.16) Manual for Polymer Dryer 1 and 2, ver 1.1  5. 3. 1.44) Manual for Spin Coater: Gamma UV, ver 1.1  5. 3. 1.21) Manual for Oven 250C, ver 1.2 | |  |